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JP 2-18412
     1990:516539 CAPLUS
AN
DN
     113:116539
     Flexible epoxy resin compositions with stable hardness
TI
IN
     Oishi, Shinji'
PA
     Sumitomo Bakelite Co., Ltd., Japan
     Jpn. Kokai Tokkyo Koho, 3 pp.
so
     CODEN: JKXXAF
DT
     Patent
LΑ
     Japanese
TC:
     ICM C08G059-32
     ICS C08G059-42; C08G059-50
CC
     37-6 (Plastics Manufacture and Processing)
FAN. CNT 1
     PATENT NO.
                     KIND DATE
                                          APPLICATION NO. DATE
     ______
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PI
     JP 02018412
                      A2
                           19900122
                                           JP 1988-167693 19880707
AB
     Title compns. contain (A) 100 parts epoxy resins contq. 30-60% bisphenol
Α
     epoxy resins having alkylene ether bonds in the main chain, (B) 5-30
parts
     aliph. mono- or diglycidyl ethers or arom. monoglycidyl ethers, and (C)
     polyamideamine (I) obtained by condensation reaction between dimer acid
     and polyamines as hardeners. Thus, a compn. comprising EP 828 (190 epoxy
     equiv) (II) 50, EP 4000 (325 epoxy equiv) 35, Eponitt 014 (alc.
     monoglycidyl ether, 215 epoxy equiv) (III) 15, and I (DSX 178, 430 amine
     value) 92 parts showed viscosity 10 P (25.degree.), Shore D hardness
     (80.degree.) 25 initially and 25 after 10 days at 80.degree., vs. 30 P,
     45, and 50, resp., for the compn. comprising II 85, III 15, and I 114
     parts.
ST
     epoxy resin blend flexibility hardness
     Epoxy resins, uses and miscellaneous
     RL: USES (Uses)
        (bisphenol A type epoxy resin blends, contq. aliph. mono- or
diglycidyl
        ethers or arom. monoglycidyl ethers and polyamideamines, with good
        flexibility)
IT
     Crosslinking agents
        (polyamideamines, from dimer acid and polyamines, epoxy resin compns.
        contg., with good flexibility)
     Epoxy resins, uses and miscellaneous
    RL: USES (Uses)
        (bisphenol A-based, epoxy resin blends, contg. aliph. mono- or
        diglycidyl ethers or arom. monoglycidyl ethers and polyamideamines,
        with good flexibility)
IT
     Polyamines
    RL: MOA (Modifier or additive use); USES (Uses)
        (polyamide-, crosslinking agents, epoxy resin compns. contq., with
good
       flexibility)
IT
     Polyamides, uses and miscellaneous
    RL: MOA (Modifier or additive use); USES (Uses)
        (polyamine-, crosslinking agents, epoxy resin compns. contg., with
good
        flexibility)
IT
    11121-15-6, EP 4000
    RL: USES (Uses)
        (bisphenol A type epoxy resin blends, contq. aliph. mono- or
        ethers or arom. monoglycidyl ethers and polyamideamines, with good
flexibility
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L5: Entry 1 of 1

File: DWPI

Jan 22, 1990

DERWENT-ACC-NO: 1990-064183

DERWENT-WEEK: 199009

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TITLE: Flexible epoxy! resin compsn. for electric parts, etc. - contains bisphenol=A epoxy resin contg. alkylene ether bonds, mono-glycidyl ether and poly-amine-amide!

PATENT-ASSIGNEE:

ASSIGNEE CODE SUMITOMO BAKELITE CO SUMB

PRIORITY-DATA:

1988JP-0167693 July 7, 1988

PATENT-FAMILY:

 PUB-NO
 PUB-DATE
 LANGUAGE
 PAGES
 MAIN-IPC

 JP 02018412 A
 January 22, 1990
 N/A
 003
 N/A

APPLICATION-DATA:

 PUB-NO
 APPL-DESCRIPTOR
 APPL-NO
 APPL-NO

 JP02018412A
 July 7, 1988
 1988JP-0167693
 N/A

INT-CL (IPC): C08G 59/32

ABSTRACTED-PUB-NO: JP02018412A

BASIC-ABSTRACT:

Compsn. comprises an epoxy resin contg. 30-60 pts.wt. bisphenol A epoxy resin having alkylene ether bonds in the main chain, 5-30 pts.wt. aliphatic mono- or diglycidyl ether or an aromatic monoglycidyl ether on the basis of 100 pts.wt. epoxy resin and a polyamineamide obtd. by the condensn. reaction of a dimer acid and a polyamine as curative.

The pref. content of polyamineamide is 80-150 pts.wt. on the basis of 100 pts.wt. of epoxy resin.

USE/ADVANTAGE - Epoxy resin compsns. have good workability by mixing with a reactive diluent used as casting materials for electric and electronic parts giving cured prods. with flexibility and a small hardness change over time.

In an example, a compsn. consisting of 50 pts. 'EP-828' (RTM) with an epoxy equiv. of 190 supplied by Shell Chemical Co., 35 pts. 'EP-4000' (RTM) with an epoxy equiv. of 325 supplied by Asahi Denka Co., 15 pts. alcohol monoglycidyl ether with an epoxy equiv. 215 ('Eponitt 014' (RTM) supplied by Nitto Kasei Co.) and 92 pts. 'DX-178' (RTM) with an amine value of 430 supplied by Henkel Hakusui Co. has a viscosity at 25 deg.C of 10 poises. A prod. obtd. by curing the compsn. for 5 hrs. at 60 deg.C has Shore D hardnesses on days 0 and 10 at 80 deg.C of 25 and 25.

CHOSEN-DRAWING: Dwg.0/0

RN 11121-15-6 REGISTRY Poly[oxy(methyl-1, 2-ethanediyl)], .alpha.,.alpha.'-((1-methylethylidene)di-4,1-phenylene]bis[.omega.-(oxiranylmethoxy)-, homopolymer (9CI) (CA INDEX NAME) OTHER NAMES: CN Adeka EP 4000 CN Adeka Resin EP 4000 CN ADK 4000 CN EP 4000 Epiclon 717 CN CN Gurishieru BPP 350 CN Rikaresin BPO 20E DR 54667-37-7, 60267-15-4, 63278-42-2, 39354-76-2 MF ((C3 H6 O)n (C3 H6 O)n C21 H24 O4)x CI PMS, COM PCT Epoxy resin, Polyether CA, CAPLUS, CHEMLIST, IFICDB, IFIPAT, IFIUDB, USPATFULL STN Files: CM 1 CRN 55236-42-5 CMF (C3 H6 O)n (C3 H6 O)n C21 H24 O4 CCI IDS, PMS

PAGE 1-A

$$CH_2-O$$
 CH_2-O
 C

PAGE 1-B

$$-(C_3H_6)$$
 \longrightarrow 0 0 0 0 0

93 REFERENCES IN FILE CA (1967 TO DATE)

23 REFERENCES TO NON-SPECIFIC DERIVATIVES IN FILE CA

93 REFERENCES IN FILE CAPLUS (1967 TO DATE)